ASSOCIATION CON ELECTRONICS IND	Material Composi © Copyright 2005. IPC, international and Pan-A	, Bannockb	urn, Illinois. A	ll rights reserved u ntions.	nder both	This docum level parts, t	ent is a declaration	ion of the succession of the s	ubstances s all lower	within the manufactur r level materials for wi	er listed i hich the n	tem. Note: i nanufacturer	f the item is an as r has engineering	sembly with lower responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier In	formation													
Company name*			Company unique ID				Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Re	epresentative*	Title - Representative				Phone - Representative*			Email - Representative*					
Product-Env-	Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Re	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type	
		LC898240-2H Motor Driver		Motor Driver			2023-06-08		P	РНМ		200.0	mg	Each
Manufactu	ring Proccess Informatio	n							ļ					
Ter	Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperatur		ure Max Time at Peak Tempera		ure Numb	per of Reflow Cyc	les	
contains Bi CU A			U Alloy	y 1			260 C 30			seconds 3				
Comments														
evel 1 - maxin	num time at peak temperature	during sol	dering is 10-3	0 seconds										
for more info	rmation regarding material con	mposition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.34	mg	Supplier	Silicon (Si)	7440-21-3		2.3274	mg
			Supplier	Polyimide	Proprietary Data		0.0126	mg
Die Attach	0.84	mg	Supplier	Silver (Ag)	7440-22-4		0.567	mg
			Supplier	Epoxy resins	129915-35-1		0.2562	mg
			Supplier	Acrylic resins	Proprietary Data		0.0168	mg
Lead Frame	20.0	mg	Supplier	Silver (Ag)	7440-22-4		0.004	mg
			Supplier	Zinc (Zn)	7440-66-6		0.038	mg
			Supplier	Iron (Fe)	7439-89-6		0.518	mg
			Supplier	Copper (Cu)	7440-50-8		19.412	mg
			Supplier	Phosphorus (P)	7723-14-0		0.028	mg
Mold Compound-Black	174.68	mg		Epoxy Phenol Resin	proprietary data		24.4552	mg
			Supplier	Carbon Black (C)	1333-86-4		0.8734	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		148.478	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.8734	mg
Plating	1.0	mg	В	Bismuth (Bi)	7440-69-9		0.006	mg
			Supplier	Tin (Sn)	7440-31-5		0.994	mg
Wire Bond - Au	1.14	mg	Supplier	Gold (Au)	7440-57-5		1.14	mg